PCN Number:		20141014002					PCN Date:		10/17/2014	
Title: Datasheet FDC1004 note added: "not tested in production"										
Customer Contact:		PCN Manager		Phone:	+1(214) 480-6037		Dept:	Qua	ality Services	
Change Type:										
Assembly Site							Wafer Bump Site			
Assembly Process							=	Wafer Bump Material		
Assembly Materials			Part number change				er Bump Process			
Mechanical Specification			Ļ	Test Site Wafer Fab Site						
Packing/Shipping/Lab		Labeling		Test Proce	ess				Materials	
							Wafer	Wafer Fab Process		
PCN Details										
Description of Change:										
Changes from Original (August 2014) to Revision A Page • Added Parameter not tested in production										
These changes may be reviewed at the datasheet links provided.										
http://ww	w.ti.com/product/	FDC1004/data	shee	t/specification	s.html?keyMatch=	=SNO	SCY5&tisea	rch=S	earch-EN	
Reason for Change:										
The note was missed during the editing of the originally published datasheet										
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):										
None										
Changes to product identification resulting from this PCN:										
None.										
Product Affected:										
FDC100)4DSCJ	FDC1004	DSC	R FDC1004DSCT						

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com